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Vishay Semiconductors

RoHS

COMPLIANT

HALOGEN FREE

GREEN

High Speed Infrared Emitting Diodes, 850 nm, **Surface Emitter Technology**



DESCRIPTION

As part of the SurfLightTM portfolio, the VSMY2853 series are infrared, 850 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- · Optical switch
- Emitter source for proximity sensors
- IR touch panels
- IR illumination
- 3D TV

FEATURES

 Package type: surface mount · Package form: GW, RGW



Peak wavelength: λ_p = 850 nm

· High reliability

High radiant power

· Very high radiant intensity

• Angle of half intensity: $\varphi = \pm 28^{\circ}$

· Suitable for high pulse current operation

· Terminal configurations: gullwing or reverse gullwing

Package matches with detector VEMD2503X01 series

Floor life: 4 weeks, MSL 2a, acc. J-STD-020

· Material categorization: For definitions of compliance please see www.vishav.com/doc?99912

PRODUCT SUMMARY					
COMPONENT	I _e (mW/sr)	φ (deg)	λ _p (nm)	t _r (ns)	
VSMY2853RG	35	± 28	850	10	
VSMY2853G	35	± 28	850	10	

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VSMY2853RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing	
VSMY2853G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing	

Note

MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	5	V
Forward current		I _F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I _{FM}	200	mA
Surge forward current	t _p = 100 μs	I _{FSM}	1	А
Power dissipation		P _V	190	mW
Junction temperature		Tj	100	°C
Operating temperature range		T _{amb}	-40 to +85	°C
Storage temperature range		T _{stg}	-40 to +100	°C
Soldering temperature	acc. figure 7, J-STD-020	T _{sd}	260	°C
Thermal resistance junction/ambient	J-STD-051, soldered on PCB	R _{thJA}	250	K/W

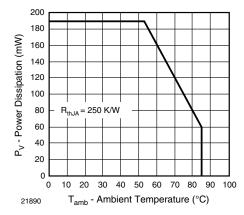


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

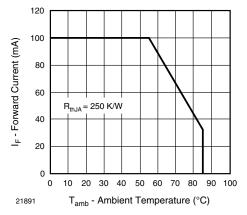


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Command valtage	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V _F		1.65	1.9	V
Forward voltage	$I_F = 1 \text{ A}, t_p = 100 \mu\text{s}$	V _F		2.9		V
Temperature coefficient of V _F	I _F = 1 mA	TK _{VF}		-1.45		mV/K
remperature coefficient of v _F	I _F = 10 mA	TK _{VF}		-1.3		mV/K
Reverse current		I _R	not designed for reverse operation		μΑ	
Junction capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0 \text{ mW/cm}^2$	CJ		125		pF
Dedicat intensity	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	l _e	20	35	50	mW/sr
Radiant intensity	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	l _e		300		mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	фe		55		mW
Temperature coefficient of radiant power	I _F = 100 mA	TΚφ _e		-0.35		%/K
Angle of half intensity		φ		± 28		deg
Peak wavelength	I _F = 100 mA	λρ	840	850	870	nm
Spectral bandwidth	I _F = 30 mA	Δλ		30		nm
Temperature coefficient of λ_p	I _F = 30 mA	TKλ _p		0.25		nm/K
Rise time	I _F = 100 mA, 20 % to 80 %	t _r		10		ns
Fall time	I _F = 100 mA, 20 % to 80 %	t _f		10		ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

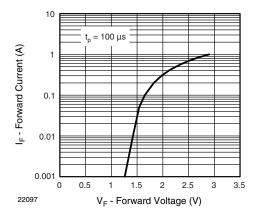


Fig. 3 - Forward Current vs. Forward Voltage

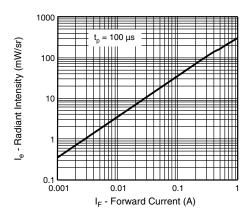


Fig. 4 - Radiant Intensity vs. Forward Current

SOLDER PROFILE

300

max. 260 255 °C 250 245 -240 °C -217 °C 200 Temperature (°C) max. 30 s 150 max. 120 max. 100 s 100 50 max. ramp up 3 °C/s max. ramp down 6 °C/s 0 0 100 150 200 250

19841 Time (s)
Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

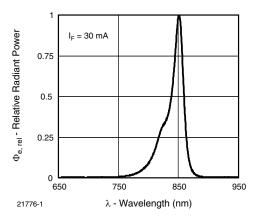


Fig. 5 - Relative Radiant Power vs. Wavelength

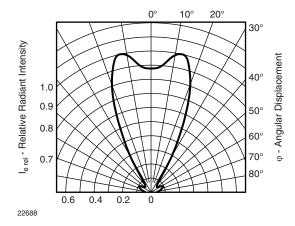


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: T_{amb} < 30 °C, RH < 60 %

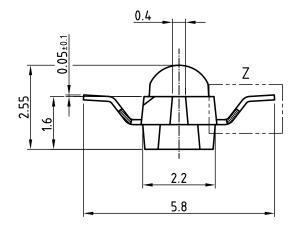
Moisture sensitivity level 2a, acc. to J-STD-020.

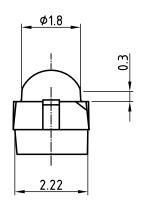
DRYING

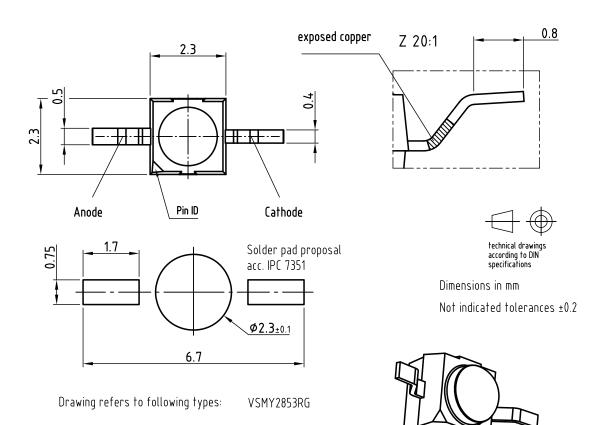
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.



PACKAGE DIMENSIONS in millimeters: VSMY2853RG

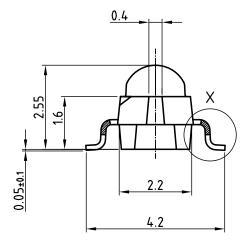


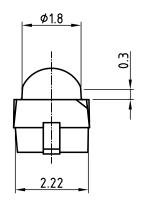


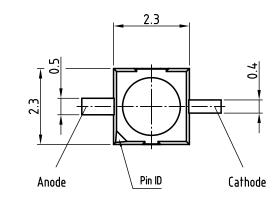


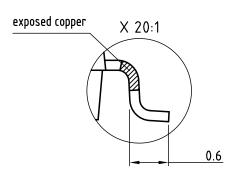
Drawing-No.: 6.544-5409.03-4 Issue: prel. 03.08.12

PACKAGE DIMENSIONS in millimeters: VSMY2853G











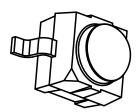
Solder pad proposal acc. IPC 7351

2.45
5.15

Dimensions in mm

Not indicated tolerances ±0.2

Drawing refers to following types: VSMY2853G

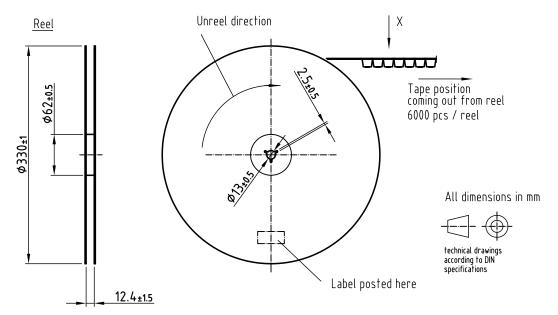


Drawing-No.: 6.544-5408.03-4

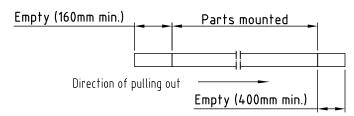
Issue: prel; 03.08.12



TAPING AND REEL DIMENSIONS in millimeters: VSMY2853RG

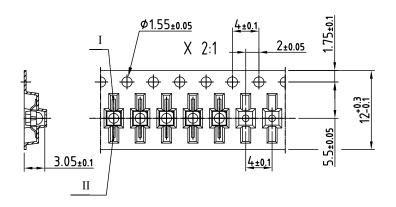


Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II	
VSMB2943RGX01			
VSMF2893RGX01	Cathode	Anode	
VEMD2x03X01	Carnoue	Alloue	
VEMT2x03X01	Collector	Emitter	
	Collector	Lilline	
VSMY2853RG	Anode	Cathode	

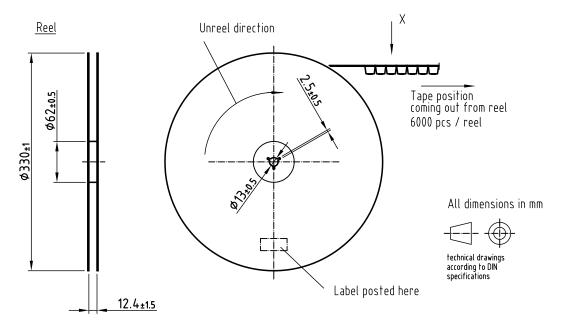


Drawing refers to following types: Reel dimensions and tape see table

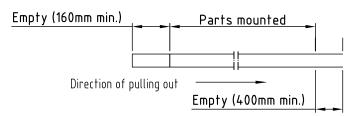
Drawing-No.: 9.800-5100.02-4

Issue: prel; 03.08.12

TAPING AND REEL DIMENSIONS in millimeters: VSMY2853G

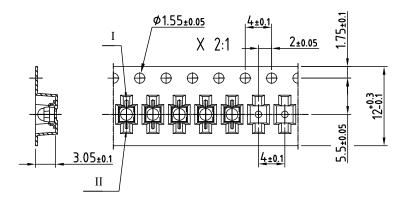


Leader and trailer tape:



Terminal position in tape

Lead I	Lead II
Cathodo	Anode
Carmode	Alloue
Callactor	Emitter
Collector	Ellitter
Anode	Cathode
	Cathode Collector



Drawing refers to following types: see table

Reel dimensions and tape

Drawing-No.: 9.800-5091.21-4

Issue: prel; 03.08.12



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